

		Telink Semiconductor (Shanghai) CO., LTD Phone: +8621 2028 1118 Fax: 8621 5038 8081 1500 Zuchongzhi Road Bldg 3 PuDong District, Shanghai, China 201203							
Composition Table									
To:		TELINK SEMICONDUCTOR (SHANGHAI) CO., LTD.							
From:		Forehope Electronic (Ningbo) Co.,Ltd.							
Product Name:		TLSR8258F512ET32							
Weight(Unit):		65.3808      mg						Date:	2024/6/25
	Material name	Vendor	Weight(mg)	Substance Name	CAS No	Weight(mg)	Content (%) Substance	Content (%) Whole chip	Content (ppm)
Die1	Telink Die	SMIC BJ	<a href="#">0.9605</a>	Silicon	7440-21-3	0.9605	100.00%	<a href="#">1.47%</a>	1000000
Die2	GD Die	SMIC BJ	<a href="#">0.2131</a>	Silicon	7440-21-3	0.2131	100.00%	<a href="#">0.33%</a>	1000000
Lead Frame	QFNWB-7X7-48L	SH Electronics	<a href="#">36.1340</a>					<a href="#">55.23%</a>	
				Copper	7440-50-8	35.0500	97.00%	53.61%	970000
				Silver	7440-22-4	0.1265	0.35%	0.19%	3500
				Iron	7439-89-6	0.8672	2.40%	1.33%	24000
				Zinc	7440-66-6	0.0542	0.15%	0.08%	1500
				Phosphorus	7723-14-0	0.0361	0.10%	0.06%	1000
DAF	ATB-F125E1-12	Henkel	<a href="#">0.0184</a>					<a href="#">0.01%</a>	
				Silicon dioxide	7631-86-9	0.0101	55.0%	0.02%	550000
				Modified epoxy resin	Trade Secret	0.0046	25.0%	0.01%	250000
				Poly[oxy[(2-oxiranyl)-1,2-cyclohexanediyl]], a-hydro-w-hydroxy-, ether with 2-ethyl-2-(hydroxymethyl)-1,3-propanediol (3:1)	244772-00-7	0.0015	8.0%	0.00%	80000
				Phenol-formaldehyde polymer	9003-35-4	0.0015	8.0%	0.00%	80000
Bisphenol-A-(epichlorhydrin)	25068-38-6	0.0007	4.0%	0.00%	40000				
Epoxy	503CuM	理均	<a href="#">0.1812</a>					<a href="#">0.17%</a>	
				Diethylene glycol monoethyl ether acetate	112-15-2	0.0083	4.6000%	0.01%	46000
				Silver flake	7440-22-4	0.1413	78.0000%	0.22%	780000
				Acylate resin	Proprietary	0.0145	8.0000%	0.02%	80000
				Epoxy resin	Proprietary	0.0163	9.0000%	0.02%	90000
Peroxide	Proprietary	0.0007	0.4000%	0.00%	4000				
Wire	SI 0.8mil	MKB	<a href="#">0.2867</a>					<a href="#">0.36%</a>	
				Silver	7440-22-4	0.2752	96.0000%	0.42%	960000
Palladium	secret	0.0115	4.0000%	0.02%	40000				
Mold Compound	CEL-9240HF10YX75C	RESONAC Materials	<a href="#">26.2109</a>					<a href="#">43.61%</a>	
				Epoxy Resin	Trade secret	1.7561	6.70%	2.69%	67000
				Phenolic Resin	Trade secret	1.3105	5.00%	2.00%	50000
				Catalyst	Trade secret	0.2621	1.00%	0.40%	10000
				Carbon black	1333-86-4	0.0786	0.30%	0.12%	3000
				Amorphous silica1	60676-86-0	20.4445	78.00%	31.27%	780000
				Amorphous silica2	7631-86-9	2.3590	9.00%	3.61%	90000
Plating	TIN	YunNan Tin	<a href="#">1.3760</a>					<a href="#">2.17%</a>	
				Tin	7440-31-5	1.3759	99.99%	2.10%	999900
other	Trade secret	0.0001	0.01%	0.00%	100				
Total			<a href="#">65.3808</a>			<a href="#">65.3808</a>	<a href="#">100%</a>	<a href="#">1000000</a>	